



University of San Carlos | Department of
COMPUTER ENGINEERING

CpE 2303L
CpE Drafting and Design

General PCB Design Considerations

General PCB Design Considerations

- The basic function of a printed circuit is to provide support for circuit components and to interconnect the components electrically.
 - Various printed wiring types have been developed (varying in base material, conductive type, number of conductor planes rigidity, etc).

General PCB Design Considerations

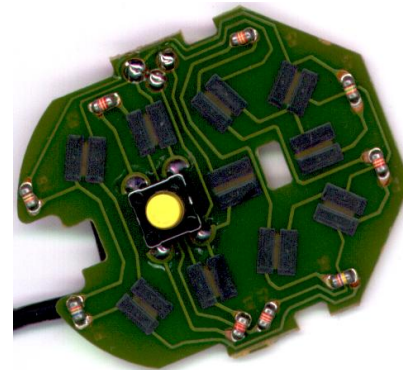
- It is expected for the PCB designers are adequately familiar with the variations and their effect on:
 - Cost
 - Component placement
 - Wiring density
 - Delivery cycles
 - Functional performance

General PCB Design Considerations

- The technical requirements that are likely to affect the design of an electrical equipment are:
 - Mechanical
 - Electrical
 - Functional
 - Environmental

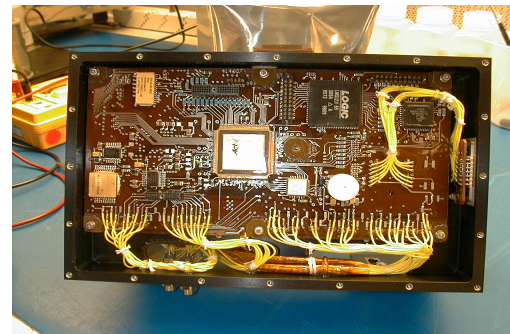
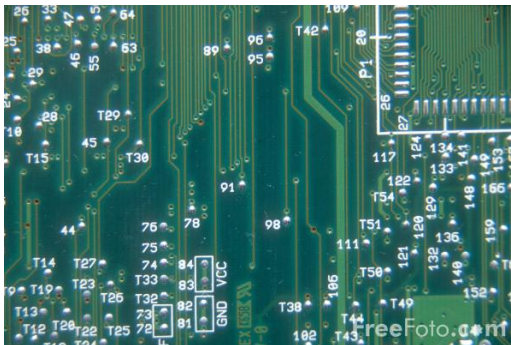
Mechanical Design

- Requirements include:
 - Size
 - Shape and weight
 - Location of components and their mounting, dimensional tolerances
 - Shielding
 - Equipment marking



Electrical Design

- Its requirements have such parameters as:
 - Circuit function and wiring distribution
 - Component selection with respect to electrical ratings, size and tolerance
 - Internal and external interconnections



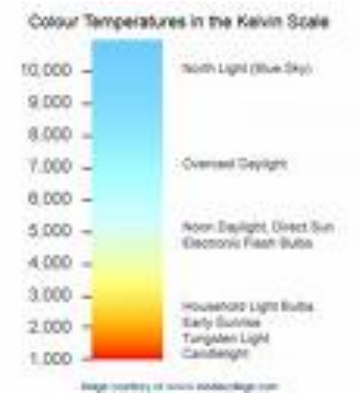
Functional Design

- Parameters include:
 - Reliability
 - Maintainability
 - Accessibility
 - Human engineering (displays, controls)



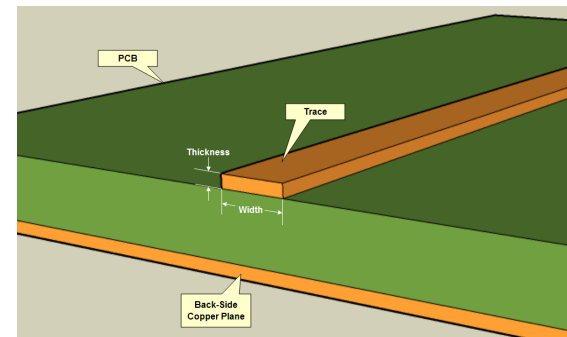
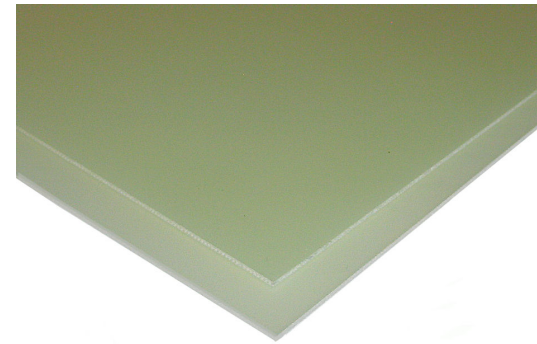
Environmental Design

- It takes into account factors such as:
 - Mechanical shock and vibration
 - Temperature extremes
 - Salt spray and fungus proofing
 - Operations in space and under water



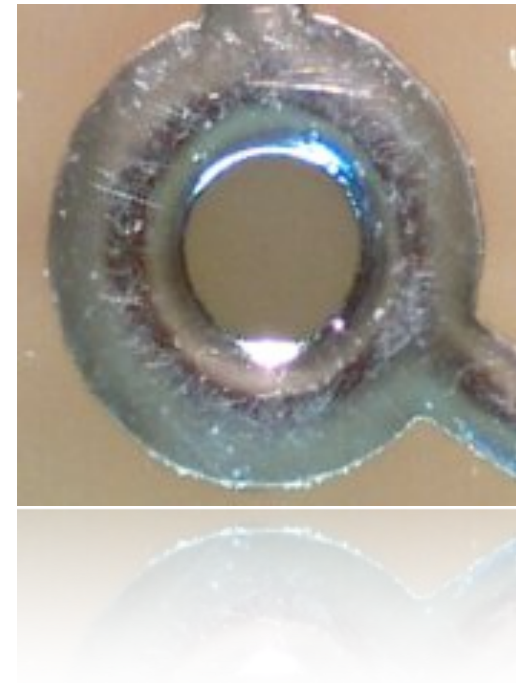
Important Design Elements

- The design inputs which should be provided by the equipment designer to the PCB designer are called *design elements*. They are:
 - Type of circuit (Analog, Digital, RF etc.)
 - Board size
 - Number of layers
 - Pad stack sizes



Important Design Elements

- Hole sizes
- Layer thickness
- Board thickness
- External connections
- Mounting holes
- Supply and ground layer thickness and
- Component details with specifications



Important Performance Parameters

- Tensile strength
- Flexural strength
- Shock and vibration
- Thermal shock and temperature cycling
- Moisture resistance
- Fungus
- Resistance
- Salt spray

Important Performance Parameters

- Warp or twist
- Dielectric breakdown
- Solderability and resolderability
- Insulation resistance
- Flame resistance
- Conductor temperature rise
- Machinability
- High altitude considerations



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End of Lecture

This material is prepared by Van B. Patiluna with contents from the reference textbook and other sources.

References:

R.S. Khandpur. Printed Circuit Boards: Design, Fabrication, Assembly and Testing. New York: McGraw-Hill, 2006.